

34mm Half Bridge IGBT Module

$V_{CES} = 1700V$, $I_C = 100A$, $V_{CE(sat)} = 1.8V$

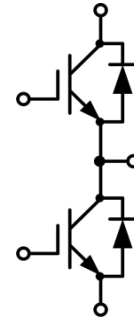
Features

- 1700V Trench-Gate / Field-Stop Technology
- Low Switching Losses
- V_{cesat} has a positive temperature coefficient



Applications

- Variable-frequency Drive / VFD
- Uninterruptible Power Supply
- Servo Drive / Servo System
- DC-AC Power Inverter



IGBT, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Collector-Emitter voltage	V_{CES}	$T_{vj}=25^{\circ}C$	1700	V
Continuous DC collector current	$I_{C\ nom}$	$T_C=100^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	100	A
Repetitive peak collector current	I_{CRM}	$t_p=1ms$	200	A
Total power dissipation	P_{tot}	$T_C=25^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	1100	W
Gate-Emitter voltage	V_{GE}		± 20	V

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Collector-Emitter saturation voltage	V_{CESat}	$V_{GE}=15V, I_C=100A$ $V_{GE}=15V, I_C=100A$ $V_{GE}=15V, I_C=100A$	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	1.8 2.05 2.1	2.3	V
Gate-Emitter threshold voltage	$V_{GE(th)}$	$I_C=6mA, V_{GE}=V_{CE}$	$T_{vj}=25^{\circ}C$	4.9	5.4	5.9
Gate charge	Q_G	$V_{GE}=-15V \dots +15V$		0.98		μC
Internal gate resistor	R_{Gint}		$T_{vj}=25^{\circ}C$	5		Ω
Input capacitance	C_{ies}	$f=100KHz, V_{CE}=25V,$ $V_{GE}=0V$	$T_{vj}=25^{\circ}C$	13.5		nF
Reverse transfer capacitance	C_{res}	$f=100KHz, V_{CE}=25V,$ $V_{GE}=0V$	$T_{vj}=25^{\circ}C$	0.4		
Collector-Emitter cut-off current	I_{CES}	$V_{CE}=1700V, V_{GE}=0V$	$T_{vj}=25^{\circ}C$		1	mA
Gate-Emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	$T_{vj}=25^{\circ}C$		100	nA
Turn-on delay time	t_{don}	$I_C=100A, V_{CE}=900V$ $V_{GE}=\pm 5V, R_G=2.5\Omega$ (inductiveload)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	169 186 191		ns

Rise time	t_r	$I_C=100A, V_{CE}=900V,$ $V_{GE}=\pm 15V, R_G=2.5\Omega$ (inductiveload)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		35 40 41		ns
Turn-off delay time	$t_{d\ off}$	$I_C=100A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=2.5\Omega$ (inductiveload)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		319 395 414		ns
Fall time	t_f	$I_C=100A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=2.5\Omega$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		358 500 506		ns
Turn-on energy loss per pulse	E_{on}	$I_C=100A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=2.5\Omega$ $di/dt=1900A/\mu s$ (inductiveload)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		13.13 18.93 21.37		mJ
Turn-off energy loss per pulse	E_{off}	$I_C=100A, V_{CE}=900V$ $V_{GE}=\pm 15V, R_G=2.5\Omega$ $dv/dt=4700V/\mu s$ (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		14.47 19.79 20.00		
SC data	I_{SC}	$V_{GE}\leq 15V, V_{CE}=1000V$ $V_{CEmax}=V_{CES}-LsCE \cdot di/dt,$ $t_P\leq 10\mu s,$	$T_{vj}=25^\circ C$		850		A
	I_{SC}	$V_{GE}\leq 15V, V_{CE}=1000V$ $V_{CEmax}=V_{CES}-LsCE \cdot di/dt,$ $t_P\leq 10\mu s,$	$T_{vj}=150^\circ C$		690		A
Thermal resistance, junction to case	R_{thJC}	per IGBT				0.130	K/W
Temperature under switching conditions	$T_{vj\ op}$			-40		150	$^\circ C$

Diode, Inverter Maximum Ratings

Parameter	Symbol	Test Condition	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^\circ C$	1700	V
Continuous DC forward current	I_F		100	A
Repetitive peak forward current	I_{FRM}	$t_p=1ms$	200	A
I^2t -value	I^2t	$t_p=10ms, \sin 180^\circ, T_j=125^\circ C$	3200	A^2s

Characteristics Values

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F=100A, V_{GE}=0V$ $T_{vj}=25^\circ C$		2.05	2.55	V
		$I_F=100A, V_{GE}=0V$ $T_{vj}=125^\circ C$		2.25		
		$I_F=100A, V_{GE}=0V$ $T_{vj}=150^\circ C$		2.2		
Peak reverse recovery current	I_{RM}	$I_F=100A$ $T_{vj}=25^\circ C$		70		A
		$-diF/dt=1900A/\mu s(T_{vj}=150^\circ C)$ $T_{vj}=125^\circ C$		73		
		$V_R=900V, V_{GE}=-15V$ $T_{vj}=150^\circ C$		76		
Recovered charge	Q_r	$I_F=100A$ $T_{vj}=25^\circ C$		10.9		$^\circ C$
		$-diF/dt=1900A/\mu s(T_{vj}=150^\circ C)$ $T_{vj}=125^\circ C$		20.6		
		$V_R=900V, V_{GE}=-15V$ $T_{vj}=150^\circ C$		23.1		
Reverse recovered energy	E_{rec}	$I_F=100A$ $T_{vj}=25^\circ C$		5.97		mJ
		$-diF/dt=1900A/\mu s(T_{vj}=150^\circ C)$ $T_{vj}=125^\circ C$		12.36		
		$V_R=900V, V_{GE}=-15V$ $T_{vj}=150^\circ C$		13.75		

Thermal resistance, junction to case	R_{thJC}	per diode			0.348	K/W
Temperature under switching conditions	T_{vjop}		-40		150	°C

Characteristics Values(Module)

Parameter	Symbol	Test Condition	Value	Unit	
Isolation test voltage	V_{ISOL}	RMS, f=50Hz, t=1min	4000	V	
Internal isolation			Al ₂ O ₃		
Storage temperature	T_{stg}		-40	125	°C
Mounting torque for module mounting	M		3	6	Nm
Weight	W		149		g

Typical Characteristics

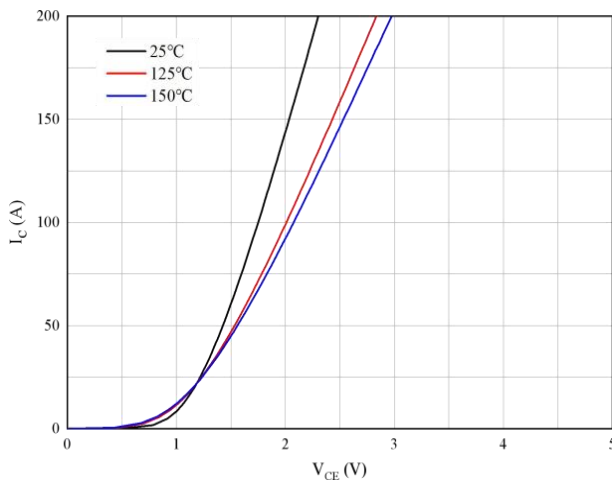


Fig 1. Typical output characteristics ($V_{GE}=15V$)

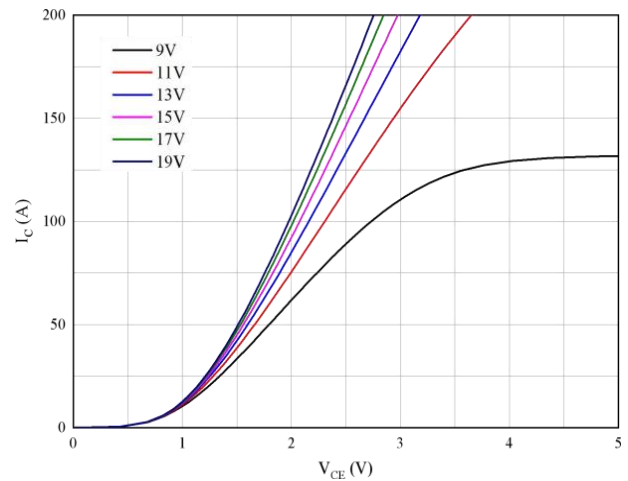


Fig 2. Typical output characteristics ($T_{vj}=150^{\circ}C$)

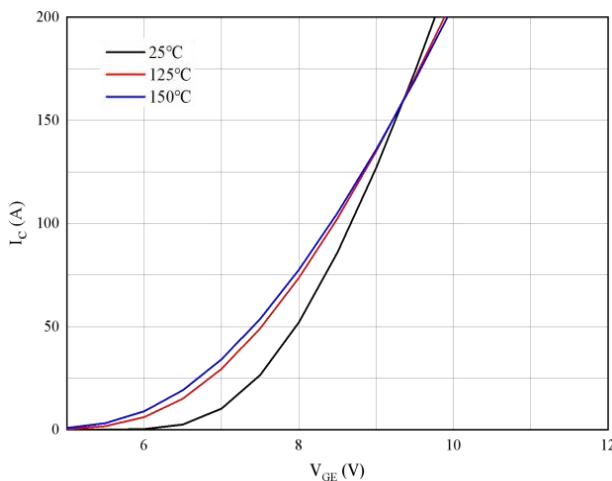


Fig 3. Typical transfer characteristics ($V_{CE}=20V$)

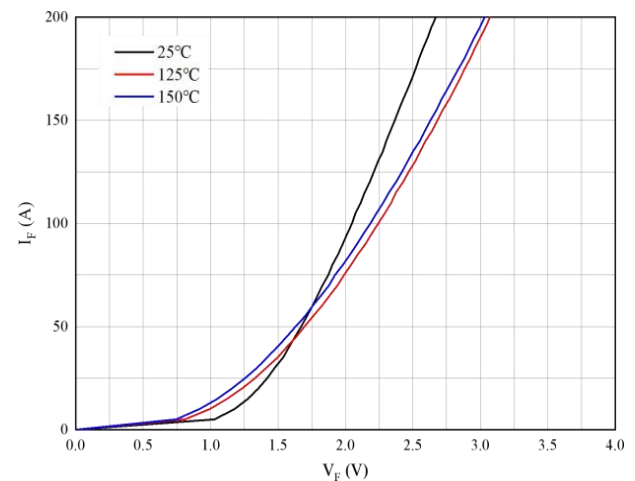


Fig 4. Forward characteristics of Diode

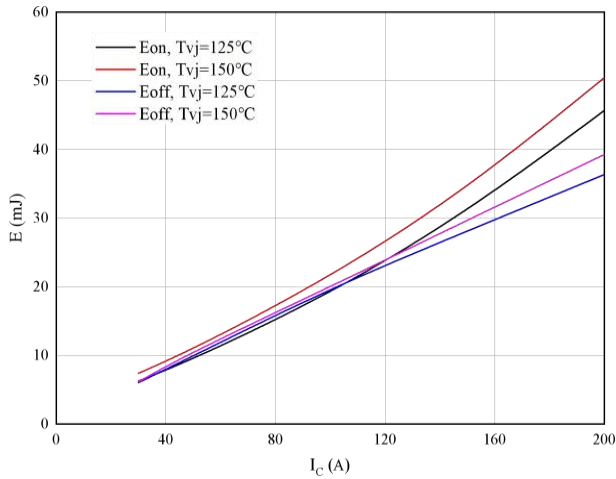


Fig 5. Switching losses of IGBT
 $V_{GE}=\pm 15\text{V}$, $R_{Gon}=2.5\Omega$, $R_{Goff}=2.5\Omega$, $V_{CE}=900\text{V}$

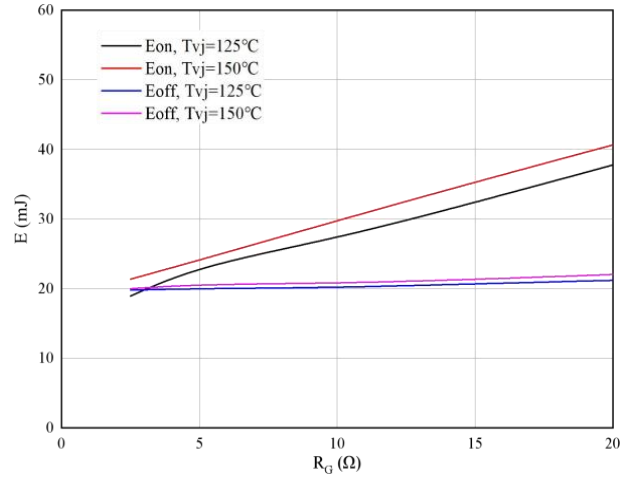


Fig 6. Switching losses of IGBT
 $V_{GE}=\pm 15\text{V}$, $I_C=100\text{A}$, $V_{CE}=900\text{V}$

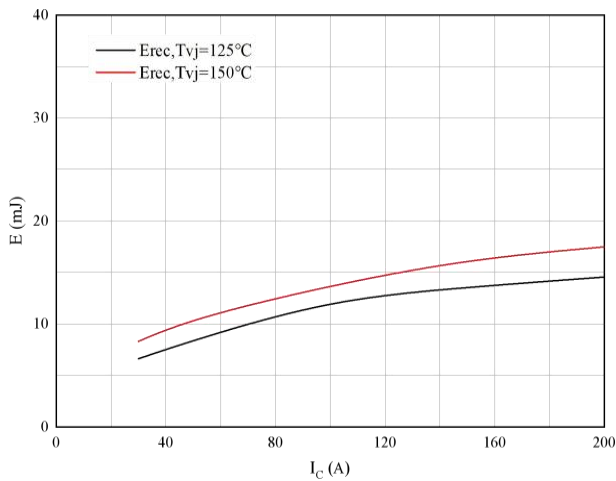


Fig 7. Switching losses of Diode
 $R_{Gon}=2.5\Omega$, $V_{CE}=900\text{V}$

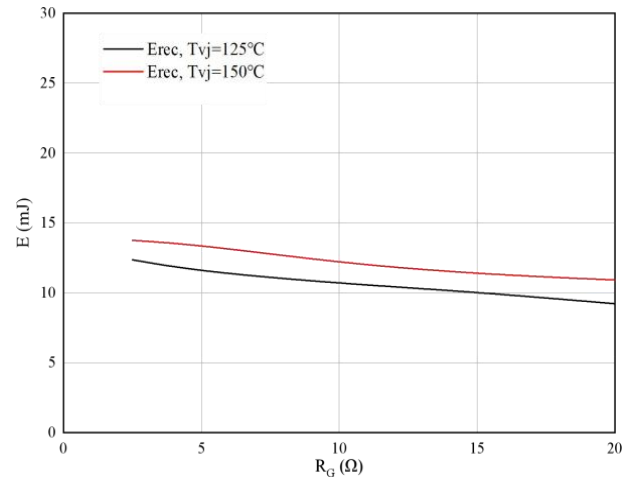


Fig 8. Switching losses of Diode
 $I_F=100\text{A}$, $V_{CE}=900\text{V}$

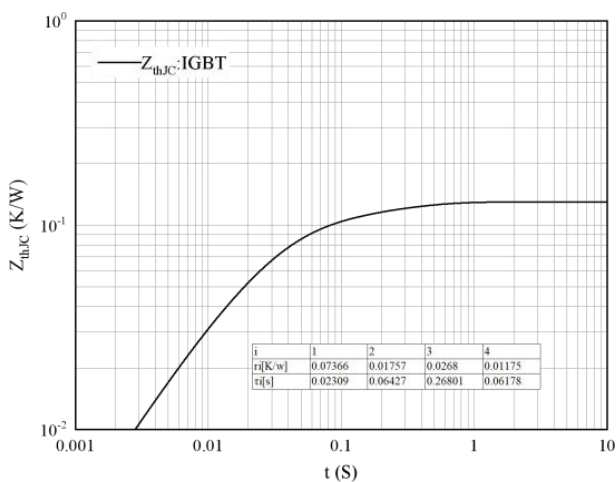


Fig 9. Transient thermal impedance IGBT, Inverter
 $Z_{thJC}=f(t)$

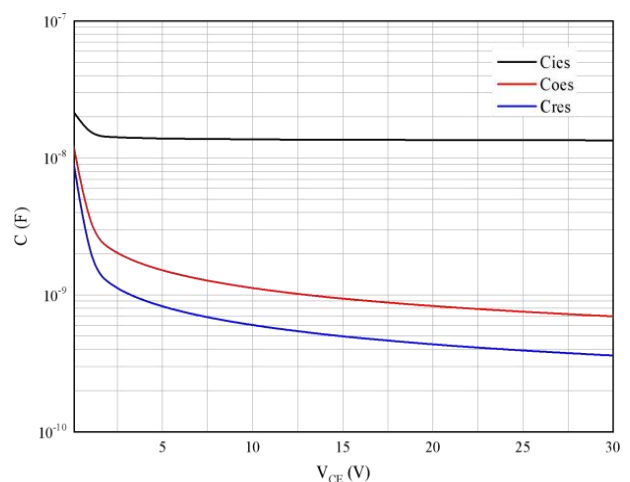


Fig 10. Capacitance characteristics

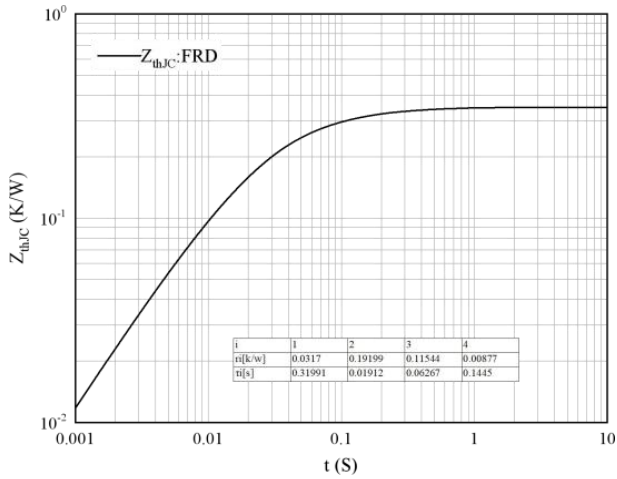
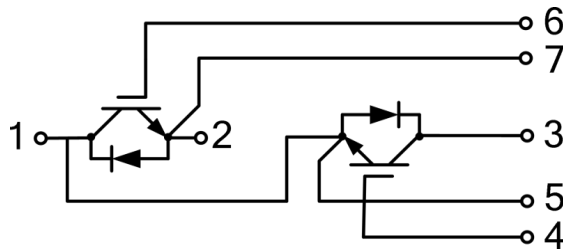
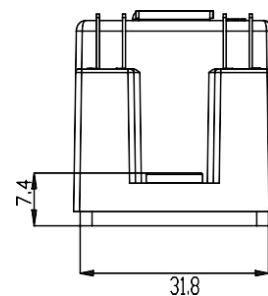
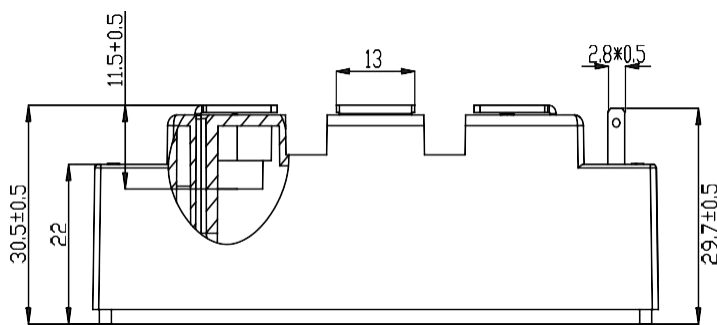
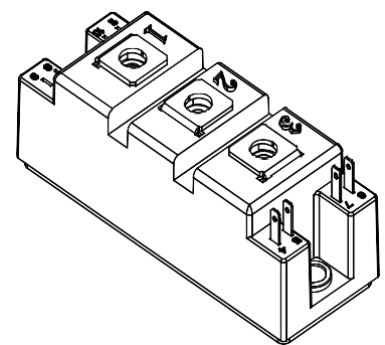
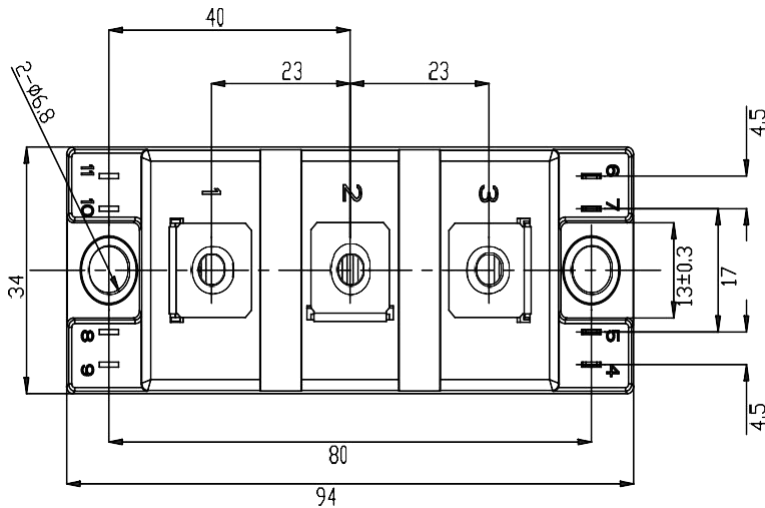


Fig 11. Transient thermal impedance FRD, Inverter
 $Z_{thJC}=f(t)$

Circuit Diagram



Package Outlines(Unit: mm)



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